

## News Release

January 8, 2015

### **Cobham Receives Class Y Certification from Defense Logistics Agency**

COLORADO SPRINGS, CO – Cobham announced today that their Semiconductor Solutions' Colorado Springs facility has received the first MIL-PRF-38535 Class Y assembly certification awarded by the Defense Logistics Agency (DLA), Land and Maritime.

DLA's December 2013 release of MIL-PRF-38535 Revision K defines, for the first time, a Class Y designation for the use of ceramic non-hermetic packages in space applications. Specifically, the Class Y designation allows for the utilization of non-hermetic flip chip package technology. The Cobham Colorado Springs facility, formerly Aeroflex, has now been certified for Class Y flip chip assembly, the result of an August 2014 DLA audit to Revision K, and the Class Y requirements described therein.

"Cobham Semiconductor Solutions is proud to receive Class Y facility certification from DLA," said Rafi Albarian, Sr. Vice President and General Manager, Cobham Semiconductor Solutions. "The Colorado Springs facility has long been certified to MIL-PRF-38535 (QML) level T, Q & V. We have since worked diligently to become certified for Class Y assembly, and are proud to be the first company to attain this status, all in the name of better serving our customers."

"This Class Y certification is a culmination of our flip chip IR&D package development effort, the hard work of our Quality Assurance organization, and our collaborative support of the JEDEC Class Y Task Group," said Dr. Scott Popelar, manager of the Cobham Advanced Packaging Engineering group. "Attaining Class Y assembly certification is a major step towards Cobham offering its customers ASIC products in a flip chip, non-hermetic package format, and keeps Cobham at the industry forefront of Class Y technology development and productization," stated Popelar.

In addition to achieving the Class Y facility certification, Cobham is also in the final stages of their Class Y flip chip assembly technology qualification. The Class Y facility certification, combined with the flip chip technology qualification, will enable Class Y

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assembly of their UT1752FC flip chip LGA/CGA package, with qualification of heat sink and decoupling capacitor attach technologies to follow. The UT1752FC package is Cobham's first Class Y standard package offering to be introduced in conjunction with their RadHard-by-Design (RHBD) 90nm technology node (UT90nHBD), both targeted for final qualification in calendar year 2015.

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Please visit [www.Cobham.com/HiRel](http://www.Cobham.com/HiRel).

### **About Cobham**

Cobham protects lives and livelihoods with its differentiated technology and know-how, operating with a deep insight into customer needs and agility. The Group offers an innovative range of technologies and services to solve challenging problems in harsh environments across commercial, defence and security markets, from deep space to the depths of the ocean, specializing in meeting the growing demand for data, connectivity and bandwidth.

Employing more than 12,000 people on five continents, the Group has customers and partners in over 100 countries, with market leading positions in: audio, video and data communications, including satellite communications; defence electronics; air-to-air refuelling; aviation services; life support and mission equipment.

### **ABOUT Cobham Semiconductor Solutions**

Cobham's Semiconductor Solutions Colorado Springs site is a supplier of semicustom and standard VLSI circuits and custom circuit card assemblies. They have a Qualified Manufacturer List (QML) certification for Class Q, Class T, Class V and Class Y.

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